

APPLIED NOKOTA® ECD

The Industry's Best Value in Wafer-Level Packaging

4 Key Features	5 Value Elements				
	On-Wafer Performance	Reliability	Wafer Protection	Extendibility	Productivity
SafeSeal™		✓	✓	✓	✓
HotSwap™		✓			✓
Engineered Modular Design		✓		✓	✓
VMax™ Chamber	✓				✓

Saves Wafers, Time, Money

>350

Hours MTBF

>330

Hours More Availability
Per Year

85,500-124,000

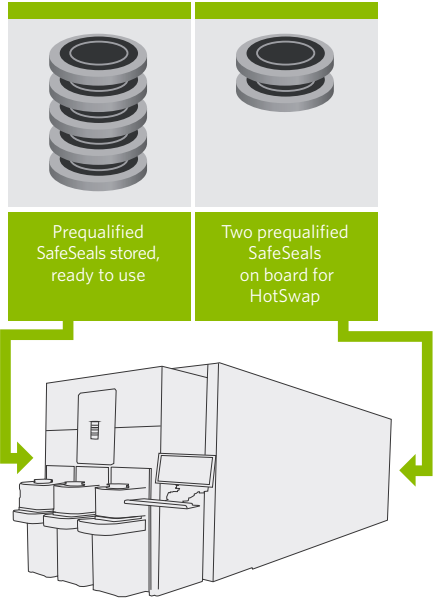
More Wafers Per Year

20-30%

Lower Capital Cost Per Wafer

Note: Bump /pillar process

40% Higher Productivity



More Revenue Per Year Per System